



AV710-VM-D

12CH VideoManagement FPGA-GPU BasedSystem



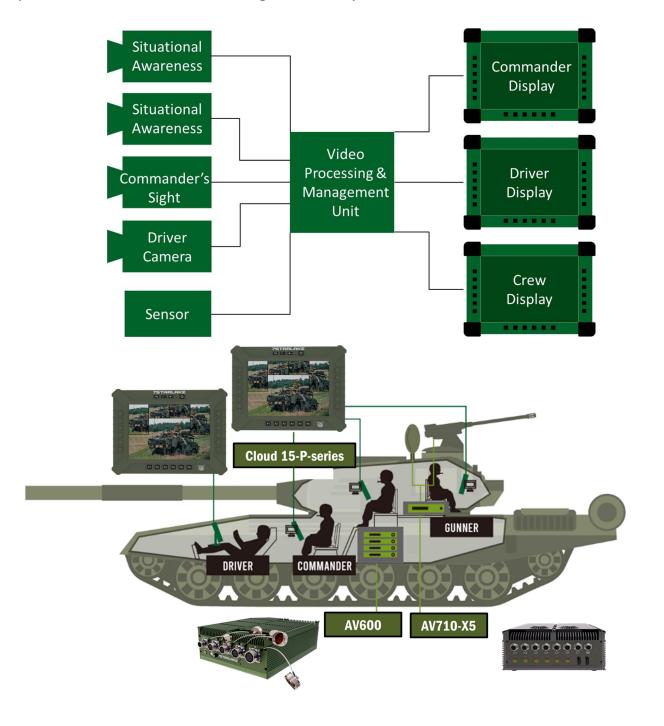
- 12 Video Input Includes 4 HD-SDI and 8 Composite (PAL)
- Support up to 4 vides output channels.
- Support Output channel a Bird's-Eye-View
- 360 Stitching View from 4 Digital Videos Channel
- Picture-In-Picture (PIP)up to 2 videos on top screen
- IP65 Sealed with External Cooling Blade
- MIL-STD-810G Thermal, Shock, Vibration, Humidity
- Power :18V~36V EMI Filter DC Input

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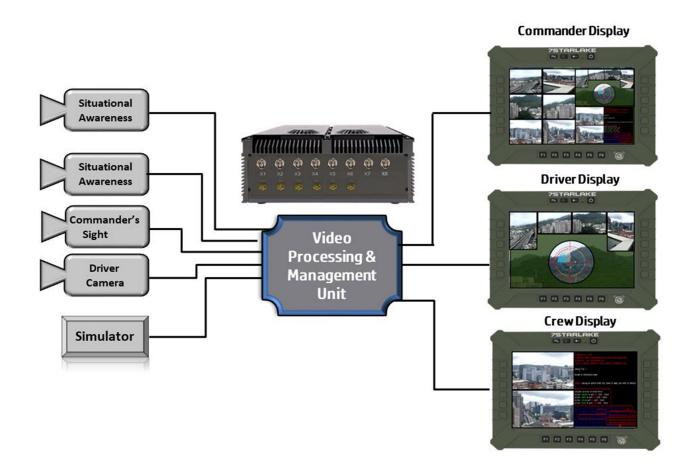
1. INTRODUCTION

Artificial intelligence is quickly becoming one of the most crucial elements of business success. Today, deploying powerful computing platforms to accelerate and scale AI-based products and services while adapting them to harsh environments has become vital in many successful military applications.7Starlake is innovating to address the emerging high-throughput inference market driven by IoTedgedevices which are generating huge amounts of data. The combination of FPGA and NVIDIA Jetson AGX is a powerful solution for demanding and latency-sensitive workloads.



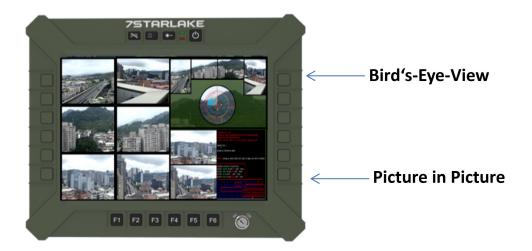
2.MAIN FEATURE

- 1. Connection to 12 Video Input channels, including 4 HD-SDI video channels and 8 composite (PAL) Channels.
- 2. Generate from 2 up to 4video output channels.
- 3. Keep Low Latencybetween input video channels and generated output video channels.
- 4. Generated Output channel a Bird's-Eye-View created from 4 SDI input channels.
- 5. Each output channel can be selected into one main channel
- 6. Up to 2 videos inserted on top screen -Picture-In-Picture (PIP).

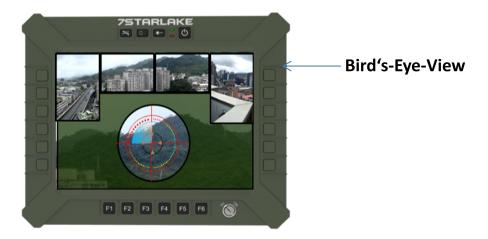


2-1 MAIN FEATURE

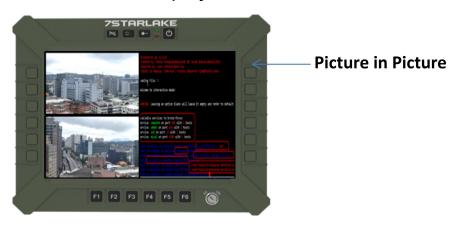
Commander Display



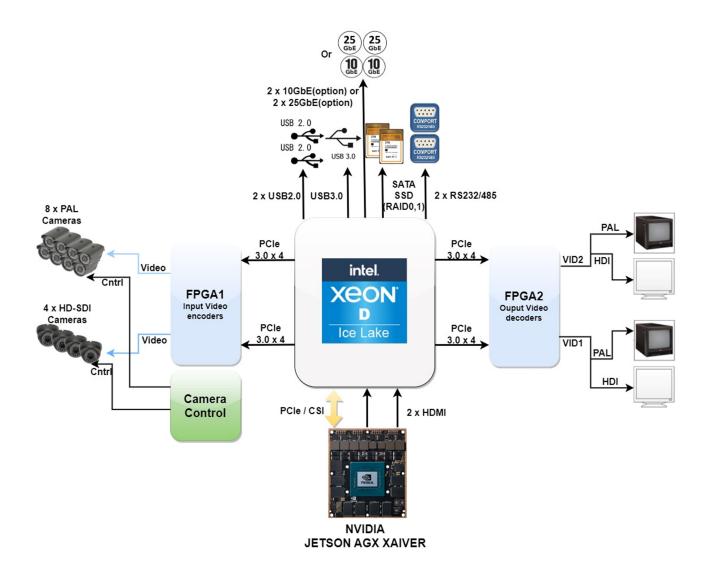
Driver Display



Crew Display



3 System Diagram



3.SYSTEM SPEC

System

	Intel® Xeon® D-2733NT, 8 core, 16 thread,15MB Cache, 2.1GHz	
CPU	Max Turbo up to 3.2GHz., up to 80W TDP	
	Intel® Xeon® D-2712T, 4 core, 8 thread,15MB Cache, 1.9GHz	
	Max Turbo up to 3.0GHz., up to 65W TDP	
Memory type	Up to 128GB ECC RDIMM, DDR4-2666MHz	
	Up to 128GB ECC/non-ECC, DDR4-2666MHz	
Chipset	Intel® SoC Integrated	
Ethernet Controller	Dual LAN with 25G LAN via SoC	
	Dual LAN with 10G LAN via Intel® X550-AT2	
LAN	2 x 10GBase-T LAN(Option) or	
	2 x 25GBase-T LAN(Option)	
Storage	2 x 2TB 2.5" SSD hot-swap, with AES function	
	1 x 2TB NVMe M.2 2280 by PCIe	
Power Type	18V~36V EMI DC Input	
Dimension	250 x350 x 100mm (W x D x H)	
Front I/O		
COM	2 x RS232/485	
LAN	2 x 10GbE (Option) or	
	2 x 25GbE(Option)	
USB3.0	1	
USB2.0	2	
Power	1 x DC-IN 18~36V	
LED	1 x SSD LED	
PW Button	Power Switch with LED indicator	
SSD	2 x SSD swap tray	
Rear I/O		
PAL Input	8	
SDI Input	4	
SDI Output	2	

Environmental

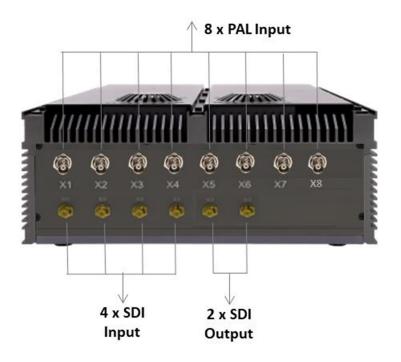
MIL-STD-810 Test	Method 500.5, Procedures I and II (Altitude, Operation): 12,192M, (40,000 ft) for the initial cabin altitude (18.8Kpa or 2.73 Psia) Method 500.5, Procedures III and IV (Altitude, Non-Operation): 15,240, (50,000 ft) for the initial cabin altitude (14.9Kpa or 2.16 Psia) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock) Method 507.5, Procedure II (Temperature & Humidity) Method 509.7 Salt Spray (50±5)g/L Method 514.6, Vibration Category 24/Non-Operating (Category 20 & 24,Vibration) Method 514.6, Vibration Category 20/Operating (Category 20 & 24,Vibration) Method 516.6, Shock-Procedure V Non-Operating (Mechanical Shock) Method 516.6, Shock-Procedure I Operating (Mechanical Shock)	
Reliability	Conduction Cooling. Designed & Manufactured using ISO 9001 Certified Quality Program.	
Operating Temp.	0 to +50°C	
Storage Temp.	-40 to +85°C	
Relative Humidity	5% to 95%, non-condensing.	
Operating System		
Operating System	Windows 10 64Bit, Linux by option	
RoHS	RoHS compliant	

4.System I/O

Front I/O



Rear I/O



6. Ordering Information

Model	AV710-VM-D4G	AV710-VM-D8F	
CPU	Intel Xeon D-2712T (4C)	Intel Xeon D-2733NT (8C)	
Memory	64 GB RDIMM ECC	128 GB RDIMM ECC	
	DDR4-2666 MHz	DDR4-2666 MHz	
GPU	Xavier AGX 32GB	Xavier AGX 64GB	
	(512 CUDA)	(512 CUDA)	
Video Input	8 PAL + 4 HD-SDI	8 PAL + 4 HD-SDI	
Video Output	2 x SDI	2 x SDI	
Storage	1x M.2 NVMe	1x M.2 NVMe	
	2 x SATA III SATASSD	4 x SATA III SATASSD	
I/O	2 x RS232/485	2 x RS232/485	
	2 x USB 2.0	2 x USB 2.0	
	2 x 10GbE (Option)	2 x 25GbE(Option)	
	1 x USB 3.0	1 x USB 3.0	
	1x DC	1x DC	
Power	18V~36V EMI DC-DC		
Dimension	250 x350 x 100mm (W x D x H)		